# **Dual J-K Flip-Flop**

The MC14027B dual J–K flip–flop has independent J, K, Clock (C), Set (S) and Reset (R) inputs for each flip–flop. These devices may be used in control, register, or toggle functions.

### **Features**

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Logic Swing Independent of Fanout
- Logic Edge-Clocked Flip-Flop Design
- Logic State is Retained Indefinitely with Clock Level Either High or Low; Information is Transferred to the Output Only on the Positive-Going Edge of the Clock Pulse
- Capable of Driving Two Low-Power TTL Loads or One Low-Power Schottky TTL Load Over the Rated Temperature Range
- Pin-for-Pin Replacement for CD4027B
- These Devices are Pb-Free and are RoHS Compliant
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

### MAXIMUM RATINGS (Voltages Referenced to V<sub>SS</sub>)

Symbol	Parameter	Value	Unit
$V_{DD}$	DC Supply Voltage Range	-0.5 to +18.0	V
V <sub>in</sub> , V <sub>out</sub>	Input or Output Voltage Range (DC or Transient)	-0.5 to V <sub>DD</sub> + 0.5	V
I <sub>in</sub> , I <sub>out</sub>	Input or Output Current (DC or Transient) per Pin	±10	mA
P <sub>D</sub>	Power Dissipation, per Package (Note 1)	500	mW
T <sub>A</sub>	Ambient Temperature Range	-55 to +125	°C
T <sub>stg</sub>	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8-Second Soldering)	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Temperature Derating:

Plastic "P and D/DW" Packages: – 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either  $V_{SS}$  or  $V_{DD}$ ). Unused outputs must be left open.



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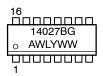
MARKING DIAGRAMS



PDIP-16 P SUFFIX CASE 648 <sup>16</sup>**ሉሉሉሉሉሉሉ** MC14027BCP o AWLYYWWG 1 ፑፑፑፑፑፑፑ



SOIC-16 D SUFFIX CASE 751B



A = Assembly Location

WL = Wafer Lot
 YY, Y = Year
 WW = Work Week
 G = Pb-Free Indicator

### **ORDERING INFORMATION**

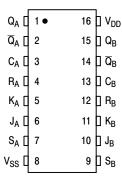
See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

TRUTH TABLE

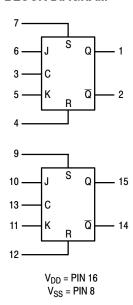
		Outputs*					
C†	J	K	S	R	Q <sub>n</sub> ‡	Q <sub>n+1</sub>	Q <sub>n+1</sub>
	1	Х	0	0	0	1	0
$\mathcal{L}$	Х	0	0	0	1	1	0
	0	Χ	0	0	0	0	1
	Х	1	0	0	1	0	1
	1	1	0	0	Qo	Qo	Qo
~	X	Χ	0	0	X	Q <sub>n</sub>	$\overline{Q_n}$
Х	Х	Χ	1	0	Х	1	0
Х	Х	Х	0	1	Х	0	1
Х	Х	Х	1	1	Х	1	1

No Change

# **PIN ASSIGNMENT**



# **BLOCK DIAGRAM**



X = Don't Care

<sup>‡ =</sup> Present State

<sup>† =</sup> Level Change

<sup>\* =</sup> Next State

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>	
MC14027BCPG	PDIP-16 (Pb-Free)	500 Units / Rail	
MC14027BDG	SOIC-16	48 Units / Rail	
NLV14027BDG*	(Pb-Free)		
MC14027BDR2G	SOIC-16	2500 Units / Tape & Reel	
NLV14027BDR2G*	(Pb-Free)		

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## **ELECTRICAL CHARACTERISTICS** (Voltages Referenced to V<sub>SS</sub>)

				- 5	5°C		25°C		125	5°C	
Characteristic	:	Symbol	V <sub>DD</sub> Vdc	Min	Max	Min	Typ (Note 2)	Max	Min	Max	Unit
Output Voltage V <sub>in</sub> = V <sub>DD</sub> or 0	"0" Level	V <sub>OL</sub>	5.0 10 15	  	0.05 0.05 0.05	_ _ _	0 0 0	0.05 0.05 0.05	_ _ _	0.05 0.05 0.05	Vdc
$V_{in} = 0$ or $V_{DD}$	"1" Level	V <sub>OH</sub>	5.0 10 15	4.95 9.95 14.95	_ _ _	4.95 9.95 14.95	5.0 10 15	_ _ _	4.95 9.95 14.95	_ _ _	Vdc
Input Voltage (V <sub>O</sub> = 4.5 or 0.5 Vdc) (V <sub>O</sub> = 9.0 or 1.0 Vdc) (V <sub>O</sub> = 13.5 or 1.5 Vdc)	"0" Level	V <sub>IL</sub>	5.0 10 15		1.5 3.0 4.0		2.25 4.50 6.75	1.5 3.0 4.0		1.5 3.0 4.0	Vdc
$(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	"1" Level	V <sub>IH</sub>	5.0 10 15	3.5 7.0 11	_ _ _	3.5 7.0 11	2.75 5.50 8.25	_ _ _	3.5 7.0 11	_ _ _	Vdc
Output Drive Current $ \begin{aligned} &(V_{OH}=2.5 \text{ Vdc})\\ &(V_{OH}=4.6 \text{ Vdc})\\ &(V_{OH}=9.5 \text{ Vdc})\\ &(V_{OH}=13.5 \text{ Vdc}) \end{aligned} $	Source	I <sub>OH</sub>	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	_ _ _ _	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	_ _ _ _	- 1.7 - 0.36 - 0.9 - 2.4	_ _ _ _	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	I <sub>OL</sub>	5.0 10 15	0.64 1.6 4.2	_ _ _	0.51 1.3 3.4	0.88 2.25 8.8	_ _ _	0.36 0.9 2.4	_ _ _	mAdc
Input Current		I <sub>in</sub>	15	_	± 0.1	_	±0.00001	± 0.1	_	± 1.0	μAdc
Input Capacitance (V <sub>in</sub> = 0)		C <sub>in</sub>	_	_	_	_	5.0	7.5	_	_	pF
Quiescent Current (Per Package)		I <sub>DD</sub>	5.0 10 15	_ _ _	1.0 2.0 4.0	_ _ _	0.002 0.004 0.006	1.0 2.0 4.0	_ _ _	30 60 120	μAdc
Total Supply Current (Not (Dynamic plus Quiesc Per Package) (C <sub>L</sub> = 50 pF on all out buffers switching)	ent,	I <sub>T</sub>	5.0 10 15			$I_T = ($	D.8 μA/kHz) f 1.6 μA/kHz) f 2.4 μA/kHz) f	+ I <sub>DD</sub> + I <sub>DD</sub>	,		μAdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

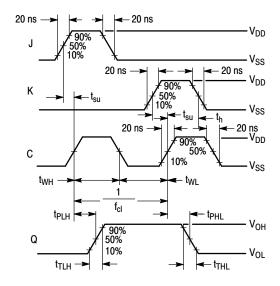
where:  $I_T$  is in  $\mu A$  (per package),  $C_L$  in pF,  $V = (V_{DD} - V_{SS})$  in volts, f in kHz is input frequency, and k = 0.002.

<sup>\*</sup>NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

# SWITCHING CHARACTERISTICS (Note 5) (CL = 50 pF, $T_A$ = 25°C)

Characteristic	Symbol	V <sub>DD</sub>	Min	Typ (Note 6)	Max	Unit
Output Rise and Fall Time $t_{TLH}, t_{THL} = (1.5 \text{ ns/pF}) \text{ C}_{L} + 25 \text{ ns} \\ t_{TLH}, t_{THL} = (0.75 \text{ ns/pF}) \text{ C}_{L} + 12.5 \text{ ns} \\ t_{TLH}, t_{THL} = (0.55 \text{ ns/pF}) \text{ C}_{L} + 12.5 \text{ ns} \\$	t <sub>TLH</sub> , t <sub>THL</sub>	5.0 10 15	_ _ _ _	100 50 40	200 100 80	ns
Propagation Delay Times**  Clock to Q, Q  t <sub>PLH</sub> , t <sub>PHL</sub> = (1.7 ns/pF) C <sub>L</sub> + 90 ns  t <sub>PLH</sub> , t <sub>PHL</sub> = (0.66 ns/pF) C <sub>L</sub> + 42 ns  t <sub>PLH</sub> , t <sub>PHL</sub> = (0.5 ns/pF) C <sub>L</sub> + 25 ns	t <sub>PLH</sub> , t <sub>PHL</sub>	5.0 10 15	_ _ _ _	175 75 50	350 150 100	ns
Set to Q, Q $t_{PLH}$ , $t_{PHL}$ = (1.7 ns/pF) $C_L$ + 90 ns $t_{PLH}$ , $t_{PHL}$ = (0.66 ns/pF) $C_L$ + 42 ns $t_{PLH}$ , $t_{PHL}$ = (0.5 ns/pF) $C_L$ + 25 ns		5.0 10 15	_ _ _	175 75 50	350 150 100	
Reset to Q, Q $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 265 \text{ ns} \\ t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 67 \text{ ns} \\ t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 50 \text{ ns}$		5.0 10 15	_ _ _	350 100 75	450 200 150	
Setup Times	t <sub>su</sub>	5.0 10 15	140 50 35	70 25 17	_ _ _	ns
Hold Times	t <sub>h</sub>	5.0 10 15	140 50 35	70 25 17	_ _ _	ns
Clock Pulse Width	t <sub>WH</sub> , t <sub>WL</sub>	5.0 10 15	330 110 75	165 55 38	_ _ _	ns
Clock Pulse Frequency	f <sub>cl</sub>	5.0 10 15	_ _ _	3.0 9.0 13	1.5 4.5 6.5	MHz
Clock Pulse Rise and Fall Time	t <sub>TLH</sub> , t <sub>THL</sub>	5.0 10 15	_ _ _	_ _ _	15 5.0 4.0	μs
Removal Times Set	t <sub>rem</sub>	5 10 15	90 45 35	10 5 3	_ _ _	ns
Reset		5 10 15	50 25 20	- 30 - 15 - 10	_ _ _	
Set and Reset Pulse Width	t <sub>WH</sub>	5.0 10 15	250 100 70	125 50 35	_ _ _	ns

<sup>5.</sup> The formulas given are for the typical characteristics only at 25°C.
6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.



Inputs R and S low. For the measurement of  $t_{WH}$ ,  $I/f_{cl}$ , and  $P_{D}$  the Inputs J and K are kept high.

Figure 1. Dynamic Signal Waveforms (J, K, Clock, and Output)

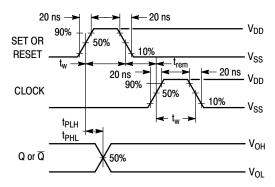
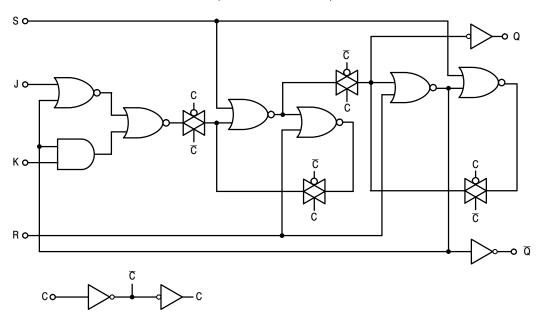


Figure 2. Dynamic Signal Waveforms (Set, Reset, Clock, and Output)

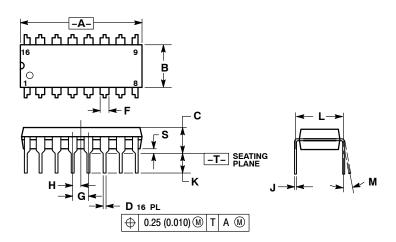
## LOGIC DIAGRAM

(1/2 of Device Shown)



# **PACKAGE DIMENSIONS**

PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08 **ISSUE T** 



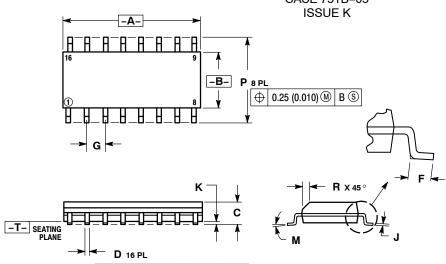
- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MIN MAX		MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100 BSC		2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
М	0°	10 °	0 °	10 °	
S	0.020	0.040	0.51	1.01	

### PACKAGE DIMENSIONS

# SOIC-16 D SUFFIX

PLASTIC SOIC PACKAGE CASE 751B-05



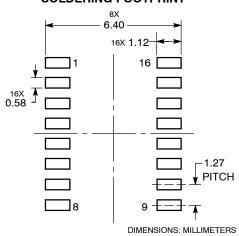
⊕ 0.25 (0.010) M T B S A S

#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
   VALEEM 1000
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.
- 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
- 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE. 5. DIMENSION D DOES NOT INCLUDE DAMBAR
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INCHES		
DIM	MIN	MIN MAX		MAX	
Α	9.80	10.00	0.386	0.393	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	BSC	0.050 BSC		
J	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
M	0°	7°	0°	7°	
P	5.80	6.20	0.229	0.244	
R	0.25	0.50	0.010	0.019	

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